



Description

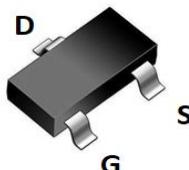
JMT N-channel Enhancement Mode Power MOSFET

Features

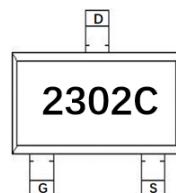
- 20V, 4A
- $R_{DS(ON)} < 29m\Omega$ @ $V_{GS} = 4.5V$
- $R_{DS(ON)} < 35m\Omega$ @ $V_{GS} = 2.5V$
- Advanced Trench Technology
- Excellent $R_{DS(ON)}$ and Low Gate Charge
- Lead Free

Applications

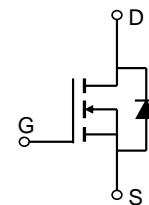
- Load Switch
- PWM Application
- Power Management



SOT-23 Top View



Marking and Pin



Schematic Diagram

Package Marking and Ordering Information

Device Marking	Device	Outline	Package	Reel Size	Reel(pcs)	Per Carton (pcs)
2302C	JMTL2302C	TAPING	SOT-23	7"	3000	120000

Absolute Maximum Ratings (@ $T_A = 25^\circ C$ unless otherwise specified)

Symbol	Parameter		Value	Units
V_{DS}	Drain-to-Source Voltage		20	V
V_{GS}	Gate-to-Source Voltage		± 12	V
I_D	Continuous Drain Current	$T_A = 25^\circ C$	4	A
		$T_A = 100^\circ C$	2.5	
I_{DM}	Pulsed Drain Current ⁽¹⁾		16	A
P_D	Power Dissipation	$T_A = 25^\circ C$	1.2	W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient ⁽²⁾		106	$^\circ C/W$
T_J, T_{STG}	Junction & Storage Temperature Range		-55 to 150	$^\circ C$



Electrical Characteristics ($T_J = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$I_D = 250\mu\text{A}, V_{GS} = 0\text{V}$	20	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 20\text{V}, V_{GS} = 0\text{V}$	-	-	1.0	μA
I_{GSS}	Gate-Body Leakage Current	$V_{DS} = 0\text{V}, V_{GS} = \pm 12\text{V}$	-	-	± 100	nA
On Characteristics						
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	0.5	0.75	1.0	V
$R_{\text{DS(ON)}}$	Static Drain-Source ON-Resistance ⁽³⁾	$V_{GS} = 4.5\text{V}, I_D = 4\text{A}$	-	22	29	$\text{m}\Omega$
		$V_{GS} = 2.5\text{V}, I_D = 3\text{A}$	-	27	35	$\text{m}\Omega$
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{GS} = 0\text{V}, V_{DS} = 10\text{V}, f = 1\text{MHz}$	-	455	-	pF
C_{oss}	Output Capacitance		-	64	-	pF
C_{rss}	Reverse Transfer Capacitance		-	55	-	pF
Q_g	Total Gate Charge	$V_{GS} = 0 \text{ to } 4.5\text{V}$ $V_{DD} = 10\text{V}, I_D = 2\text{A}$	-	6	-	nC
Q_{gs}	Gate Source Charge		-	1	-	nC
Q_{gd}	Gate Drain("Miller") Charge		-	1.5	-	nC
Switching Characteristics						
$t_{d(on)}$	Turn-On Delay Time	$V_{GS} = 4.5\text{V}, V_{DD} = 10\text{V}$ $I_D = 2\text{A}, R_{\text{GEN}} = 3\Omega$	-	4	-	ns
t_r	Turn-On Rise Time		-	13	-	ns
$t_{d(off)}$	Turn-Off Delay Time		-	65	-	ns
t_f	Turn-Off Fall Time		-	33	-	ns
Drain-Source Diode Characteristics and Max Ratings						
I_S	Maximum Continuous Drain to Source Diode Forward Current	-	-	4	A	
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current	-	-	16	A	
V_{SD}	Drain to Source Diode Forward Voltage	$V_{GS} = 0\text{V}, I_S = 4\text{A}$	-	-	1.2	V
trr	Body Diode Reverse Recovery Time	$I_F = 2\text{A}, di/dt = 60\text{A/us}$	-	6	-	ns
Qrr	Body Diode Reverse Recovery Charge		-	0.8	-	nC

Notes:

1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.

2. $R_{\theta JA}$ is measured with the device mounted on a 1inch² pad of 2oz copper FR4 PCB

3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 0.5\%$.

Typical Performance Characteristics

Figure 1: Output Characteristics

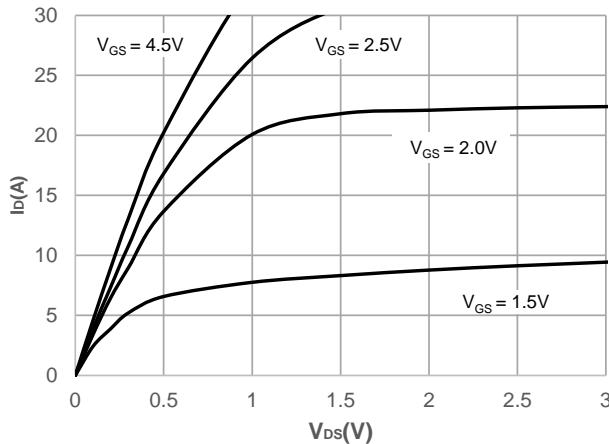


Figure 2: Typical Transfer Characteristics

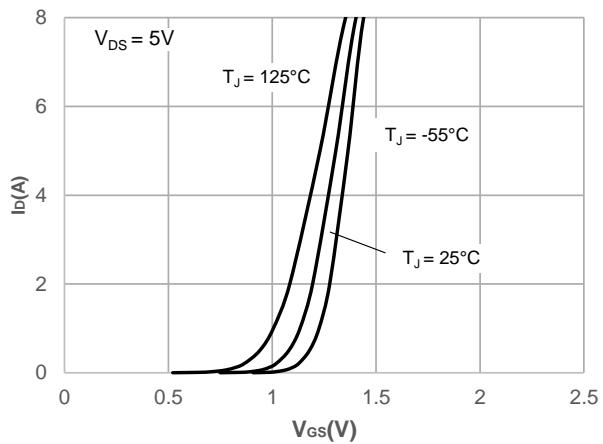


Figure 3: On-resistance vs. Drain Current

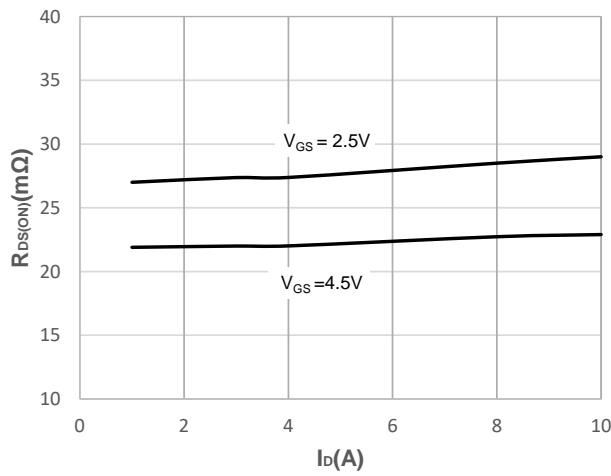


Figure 4: Body Diode Characteristics

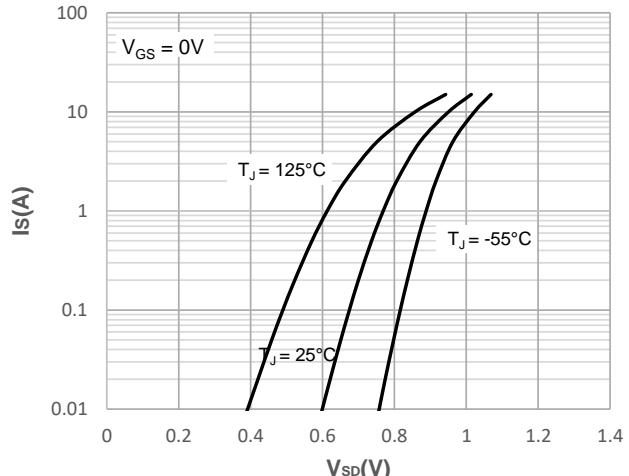


Figure 5: Gate Charge Characteristics

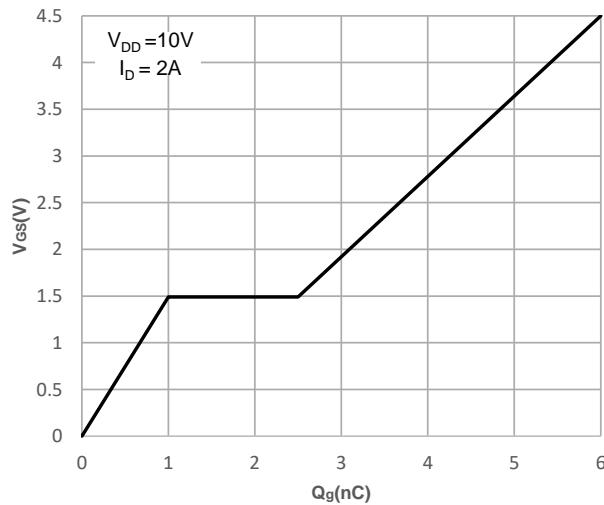
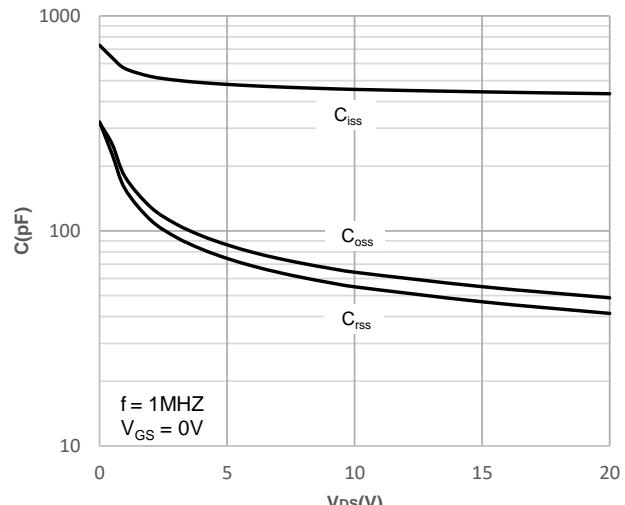


Figure 6: Capacitance Characteristics



Typical Performance Characteristics

Figure 7: Normalized Breakdown voltage vs. Junction Temperature

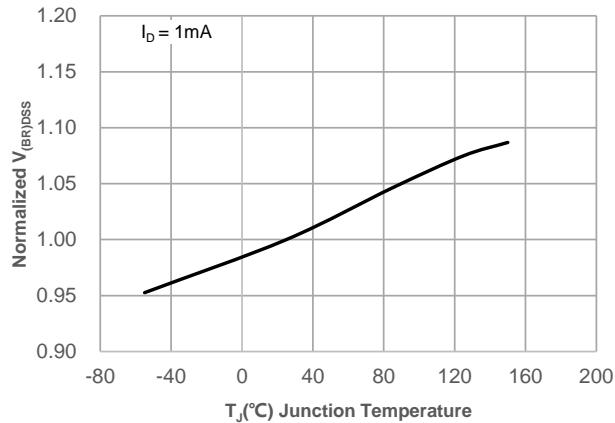


Figure 8: Normalized on Resistance vs. Junction Temperature

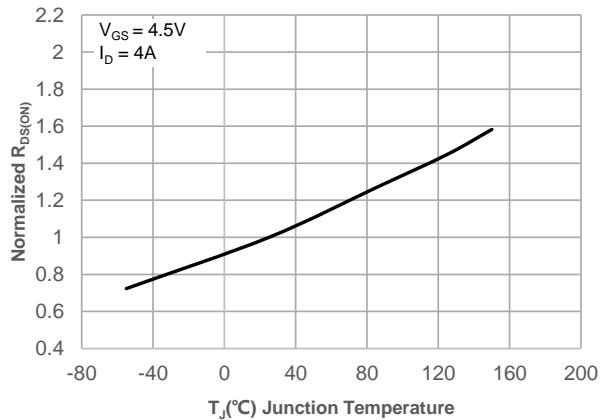


Figure 9: Maximum Safe Operating Area

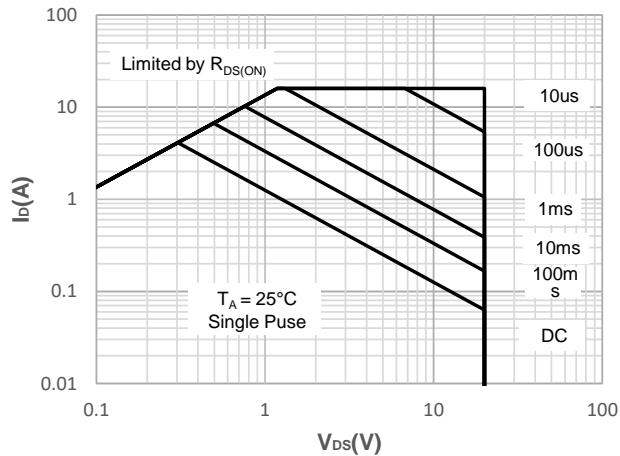


Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature

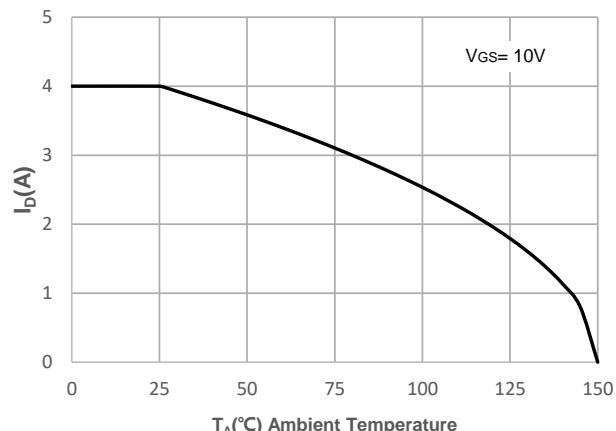


Figure 11: Normalized Maximum Transient Thermal Impedance

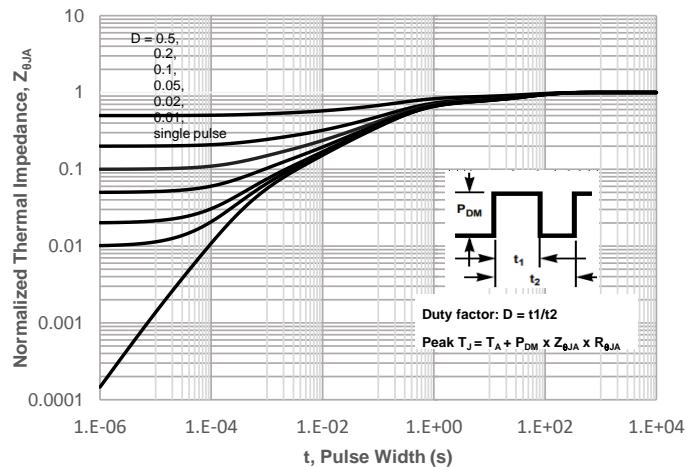
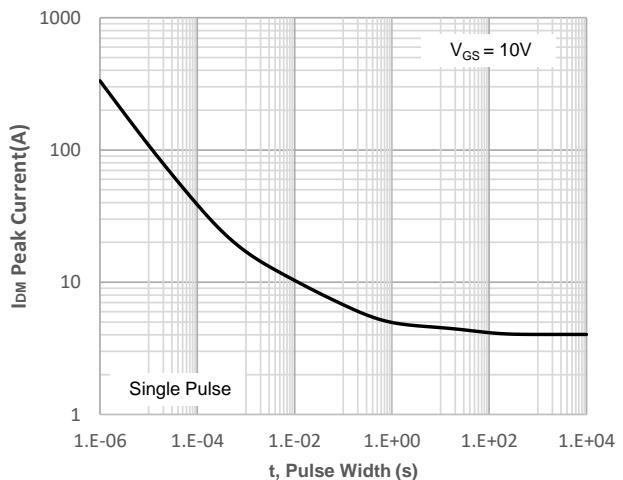


Figure 12: Peak Current Capacity



Test Circuit

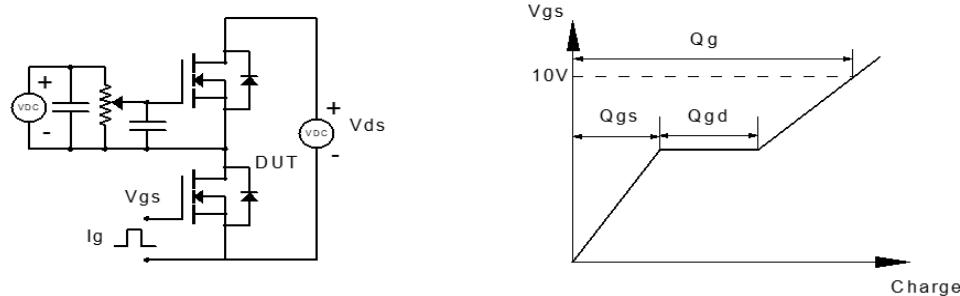


Figure 1: Gate Charge Test Circuit & Waveform

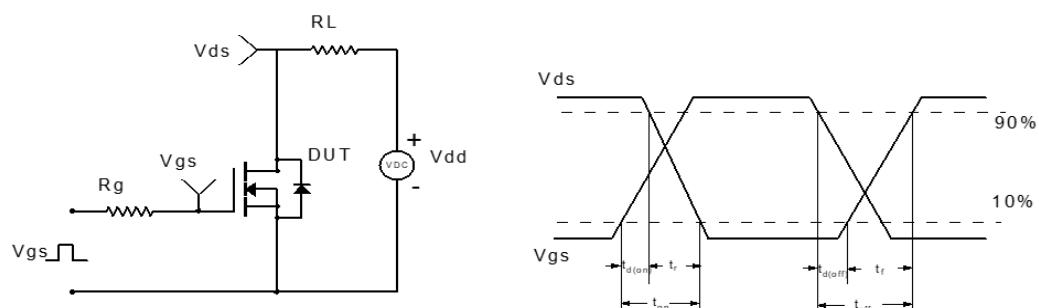


Figure 2: Resistive Switching Test Circuit & Waveform

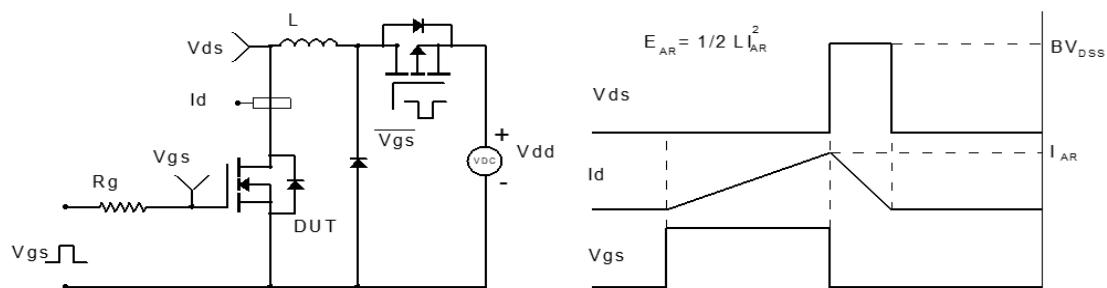


Figure 3: Unclamped Inductive Switching Test Circuit & Waveform

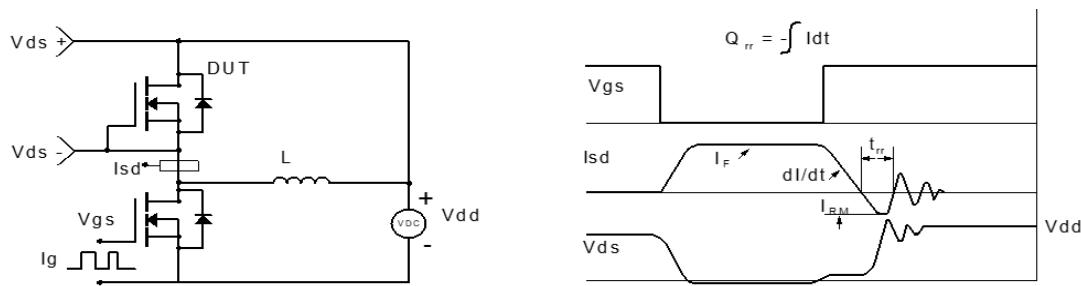
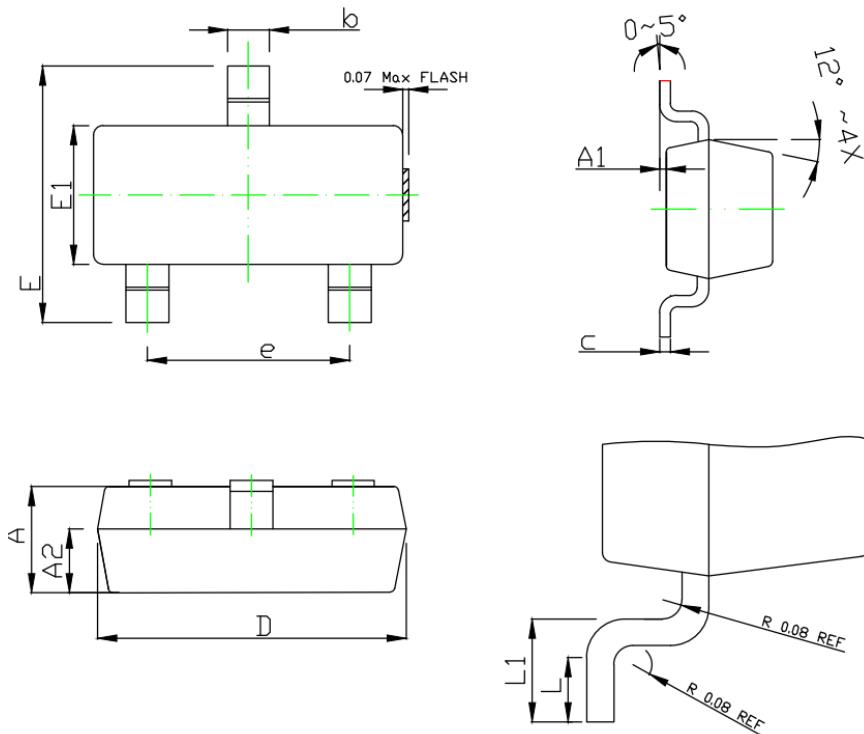


Figure 4: Diode Recovery Test Circuit & Waveform

Package Mechanical Data(SOT-23)



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	0.95	1.00	1.05
A1	0.01	0.05	0.10
b	0.35	0.40	0.45
c	0.11 BSC		
D	2.80	2.90	3.00
E	2.30	2.40	2.50
E1	1.20	1.30	1.40
e	0.95BSC		
L	0.20	-	-
L1	0.30	0.40	0.50
A2	0.60	REF	

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